



High-end Power Semiconductor Manufacturer

KP2000A 2000V-2800V

Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications



Mean on-state current	I_{TAV}	2000 A			
Repetitive peak off-state voltage	V_{DRM}	2000 – 2800 V			
Repetitive peak reverse voltage	V_{RRM}				
Turn-off time	t_q	500 μ s			
V_{DRM}, V_{RRM}, V	2000	2200	2400	2600	2800
Voltage code	20	22	24	26	28
$T_{j}, ^\circ C$	-60 – 125				

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	2000	$T_c=85^\circ C$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	3140	$T_c=85^\circ C$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	50.0 58.0	$T_j=T_{j\max}$ $T_j=25^\circ C$	180° half-sine wave; 50 Hz ($t_p=10$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μ s; $di_G/dt=1$ A/ μ s
			53.0 61.0	$T_j=T_{j\max}$ $T_j=25^\circ C$	180° half-sine wave; 60 Hz ($t_p=8.3$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μ s; $di_G/dt=1$ A/ μ s
I^2t	Safety factor	$A^2s \cdot 10^3$	12500 16820	$T_j=T_{j\max}$ $T_j=25^\circ C$	180° half-sine wave; 50 Hz ($t_p=10$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μ s; $di_G/dt=1$ A/ μ s
			11655 15440	$T_j=T_{j\max}$ $T_j=25^\circ C$	180° half-sine wave; 60 Hz ($t_p=8.3$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=500$ μ s; $di_G/dt=1$ A/ μ s
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000–2800	$T_{j\min} < T_j < T_{j\max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100–2900	$T_{j\min} < T_j < T_{j\max}$; 180° half-sine wave; 50 Hz; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.75 \cdot V_{DRM}$ $0.75 \cdot V_{RRM}$	$T_j=T_{j\max}$; Gate open	

TRIGGERING				
I_{FGM}	Peak forward gate current	A	10	$T_j = T_{j\ max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	5	$T_j = T_{j\ max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/ μ s	630	$T_j = T_{j\ max}; V_D = 0.67 \cdot V_{DRM}; I_{TM} = 2 I_{TAV};$ Gate pulse: $I_G = I_{FGM}; V_G = 20\ V;$ $t_{GP} = 500\ \mu s; di_G/dt = 1\ A/\mu s$
THERMAL				
T_{stg}	Storage temperature	$^{\circ}C$	-60 – 125	
T_j	Operating junction temperature	$^{\circ}C$	-60 – 125	
MECHANICAL				
F	Mounting force	kN	40.0 – 50.0	
a	Acceleration	m/s^2	50 100	Device unclamped Device clamped

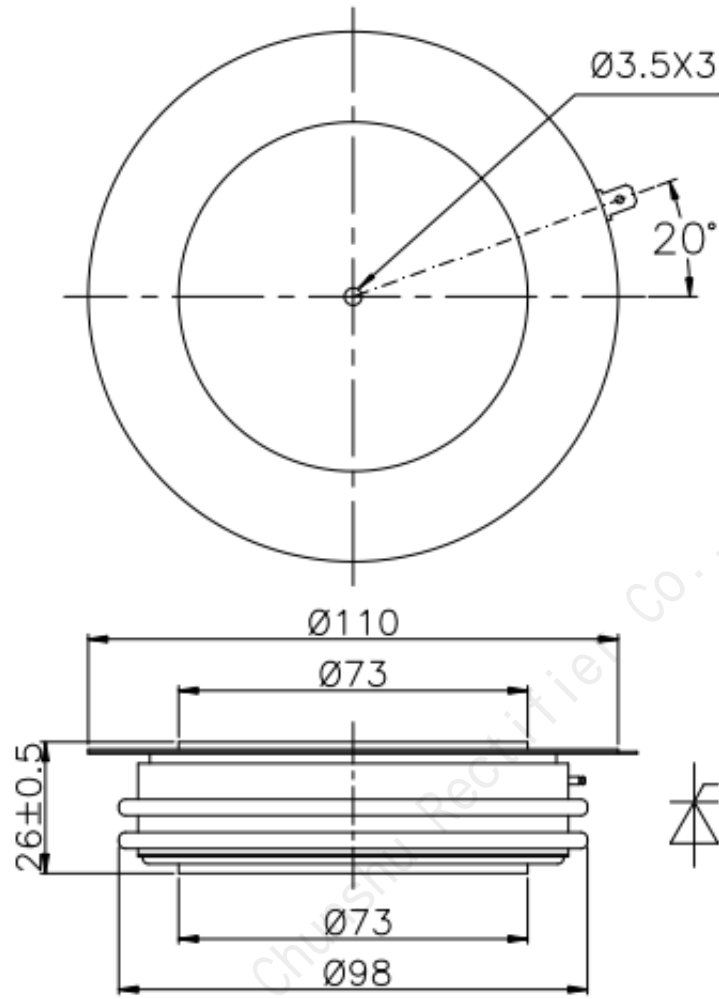
CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	1.70	$T_j = 25\ ^{\circ}C; I_{TM} = 6280\ A$	
$V_{T(TO)}$	On-state threshold voltage, max	V	1.00	$T_j = T_{j\ max};$	
r_T	On-state slope resistance, max	$m\Omega$	0.140	$0.5\ \pi\ I_{TAV} < I_T < 1.5\ \pi\ I_{TAV}$	
I_L	Latching current, max	mA	1500	$T_j = 25\ ^{\circ}C; V_D = 12\ V;$ Gate pulse: $I_G = I_{FGM}; V_G = 20\ V;$ $t_{GP} = 500\ \mu s; di_G/dt = 1\ A/\mu s$	
I_H	Holding current, max	mA	300	$T_j = 25\ ^{\circ}C;$ $V_D = 12\ V;$ Gate open	
BLOCKING					
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	200	$T_j = T_{j\ max};$ $V_D = V_{DRM}; V_R = V_{RRM}$	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	1000	$T_j = T_{j\ max};$ $V_D = 0.67 \cdot V_{DRM};$ Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.00	$T_j = 25\ ^{\circ}C$ $T_j = T_{j\ max}$	$V_D = 12\ V; I_D = 3\ A;$ Direct gate current
I_{GT}	Gate trigger direct current, max	mA	300 200	$T_j = 25\ ^{\circ}C$ $T_j = T_{j\ max}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j\ max};$ $V_D = 0.67 \cdot V_{DRM};$	
I_{GD}	Gate non-trigger direct current, min	mA	15.00	Direct gate current	
SWITCHING					
t_{gd}	Delay time	μs	2.50	$T_j = 25\ ^{\circ}C; V_D = 0.4 \cdot V_{DRM}; I_{TM} = I_{TAV};$ Gate pulse: $I_G = I_{FGM}; V_G = 20\ V;$ $t_{GP} = 500\ \mu s; di_G/dt = 1\ A/\mu s$	
t_q	Turn-off time ²⁾ , max	μs	500	$dv_D/dt = 50\ V/\mu s; T_j = T_{j\ max}; I_{TM} = I_{TAV};$ $di_R/dt = -10\ A/\mu s; V_R = 100V;$ $V_D = 0.67 \cdot V_{DRM}$	
Q_{rr}	Total recovered charge, max	μC	4700	$T_j = T_{j\ max}; I_{TM} = 2000\ A;$	
t_{rr}	Reverse recovery time, max	μs	40	$di_R/dt = -10\ A/\mu s;$	
I_{rrM}	Peak reverse recovery current, max	A	235	$V_R = 100\ V$	

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	°C/W	0.0085	Direct current	Double side cooled
R_{thjc-A}			0.0187		Anode side cooled
R_{thjc-K}			0.0153		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	°C/W	0.0020	Direct current	
MECHANICAL					
w	Weight, typ	g	1500		
D_s	Surface creepage distance	mm (inch)	36.60 (1.441)		
D_a	Air strike distance	mm (inch)	16.20 (0.638)		

Beijing Xinchuang Chunshu Rectifier Co., Ltd

OVERALL DIMENSIONS



KT80

All dimensions in millimeters

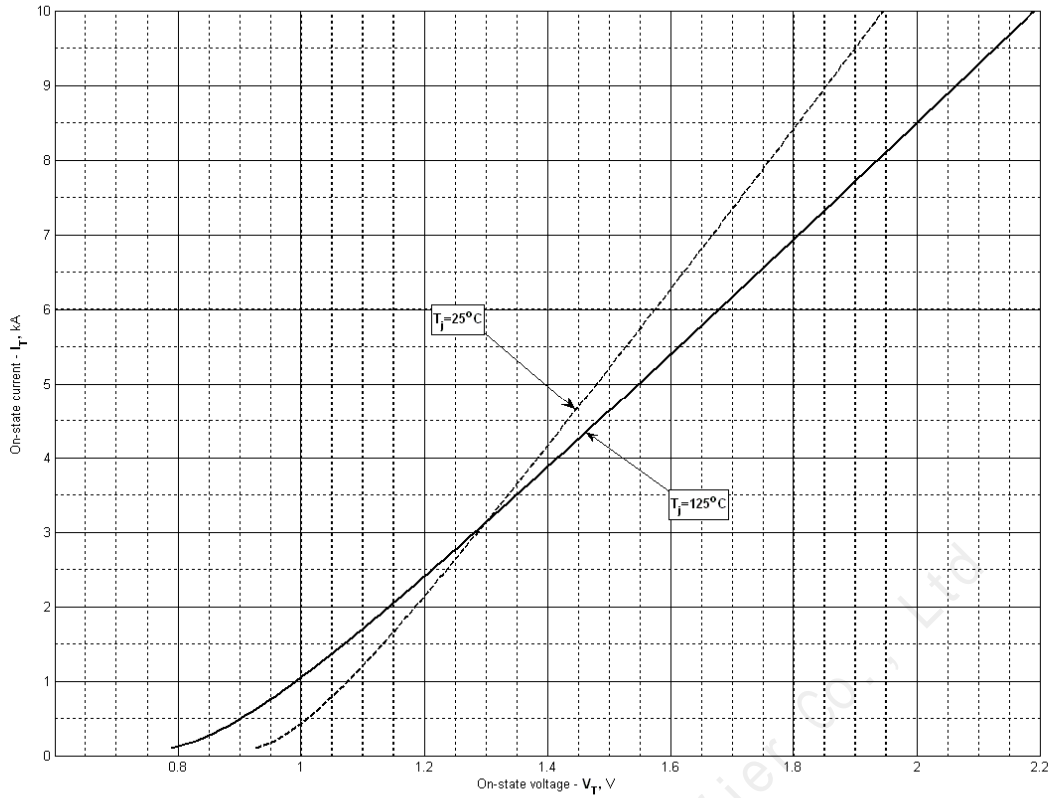


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j \max}$
A	0.837909	0.670342
B	0.057589	0.081048
C	-0.206887	-0.276312
D	0.324522	0.433423

On-state characteristic model (see Fig. 1)

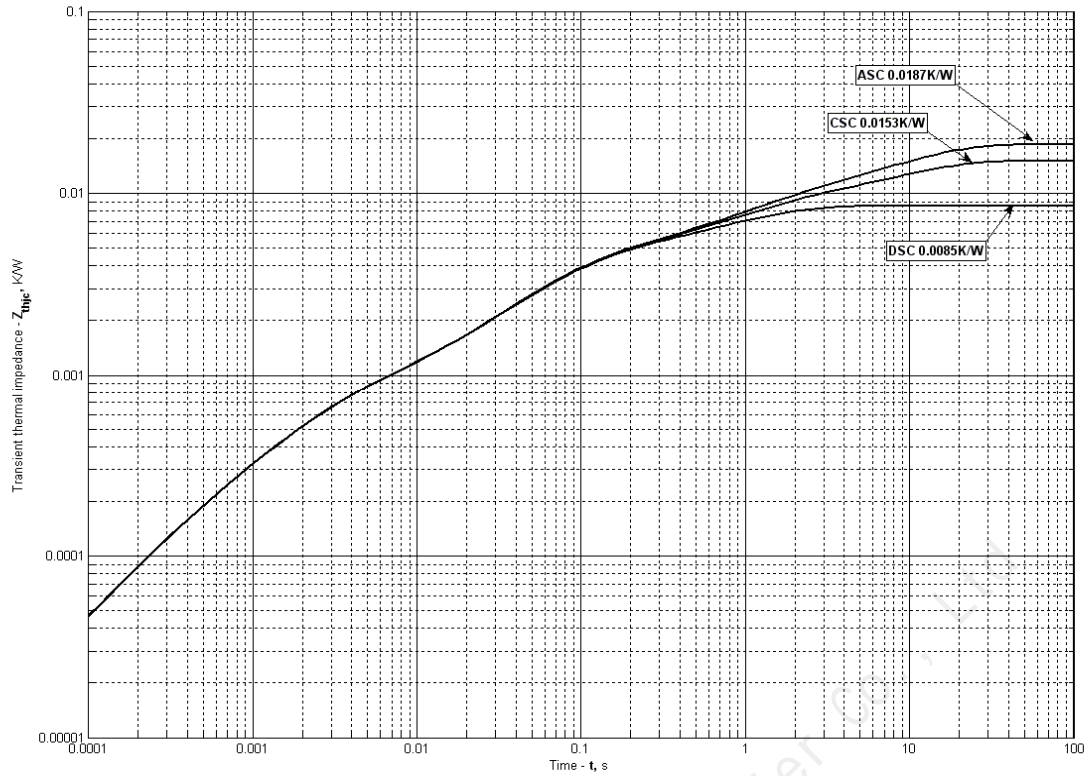


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i K/W	0.00007989	0.002973	0.0005936	0.000846	0.00005975	0.003948
τ_i S	1.688	0.06219	0.002329	0.138	0.0003243	0.9533

DC Anode side cooled

i	1	2	3	4	5	6
R_i K/W	0.01013	0.004062	0.0009401	0.002853	0.0005963	0.00005641
τ_i S	9.747	1.058	0.1304	0.06179	0.002313	0.0003013

DC Cathode side cooled

i	1	2	3	4	5	6
R_i K/W	0.006619	0.004034	0.0008595	0.002956	0.0005965	0.00005689
τ_i S	9.744	1.025	0.1394	0.06237	0.002318	0.0003037

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

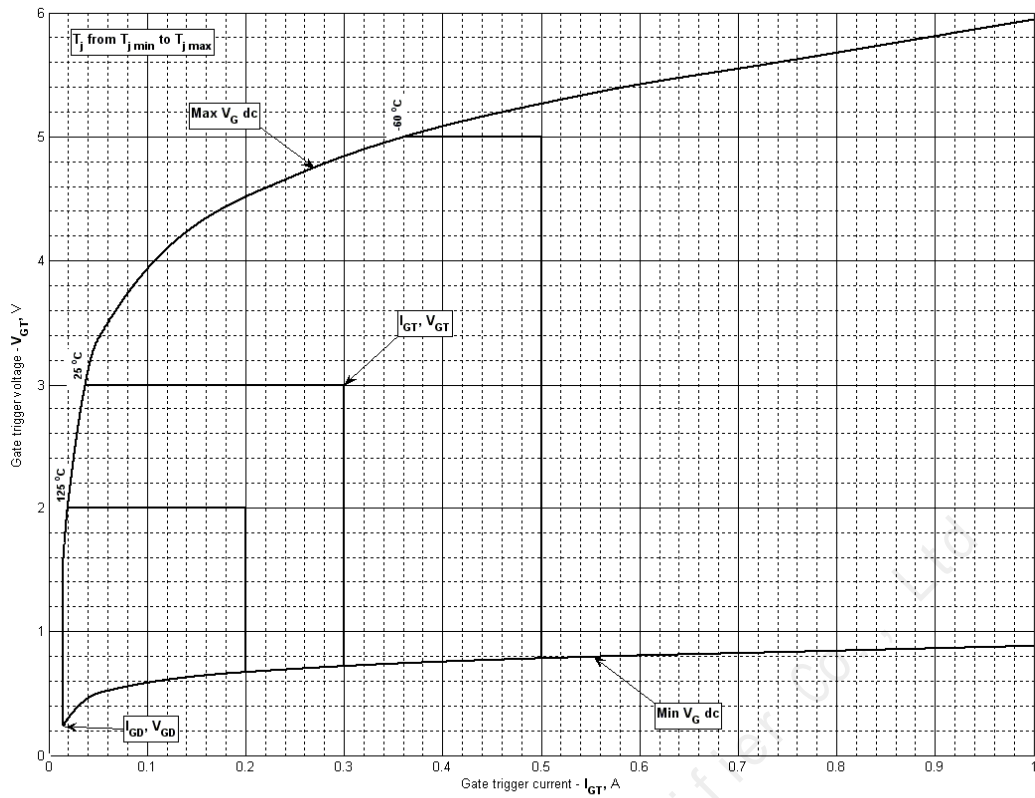


Fig 3 – Gate characteristics – Trigger limits

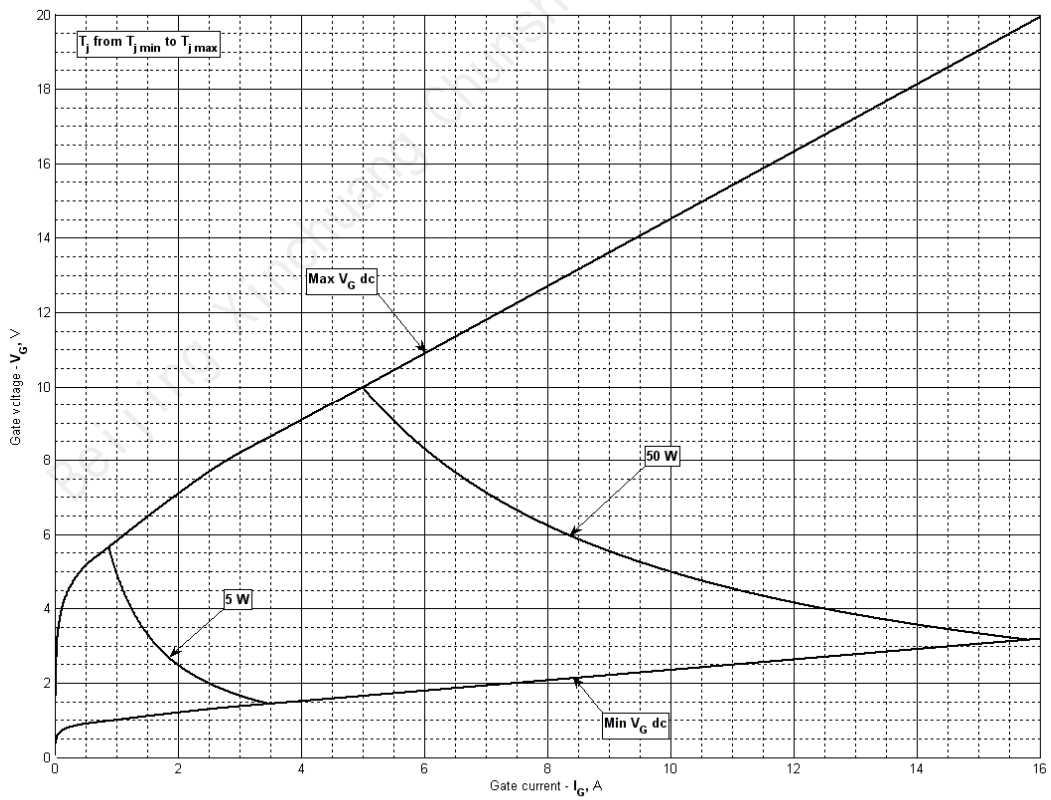


Fig 4 - Gate characteristics – Power curves

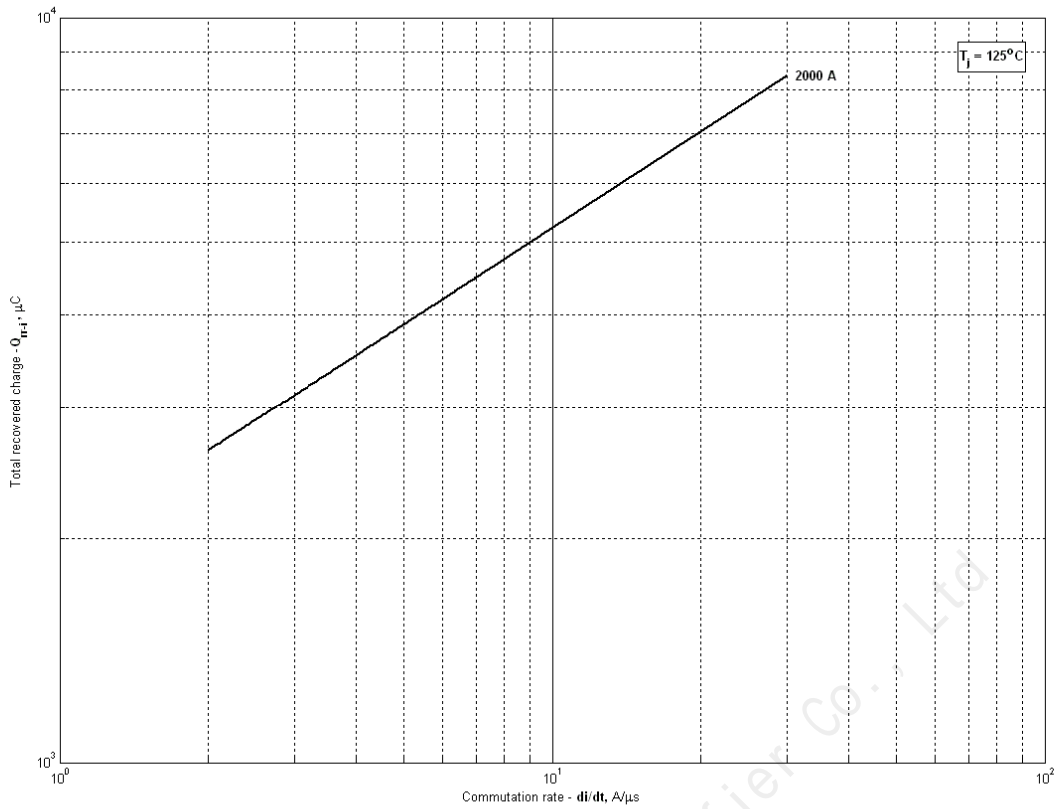


Fig 5 – Total recovered charge, Q_{rr-i} (integral)

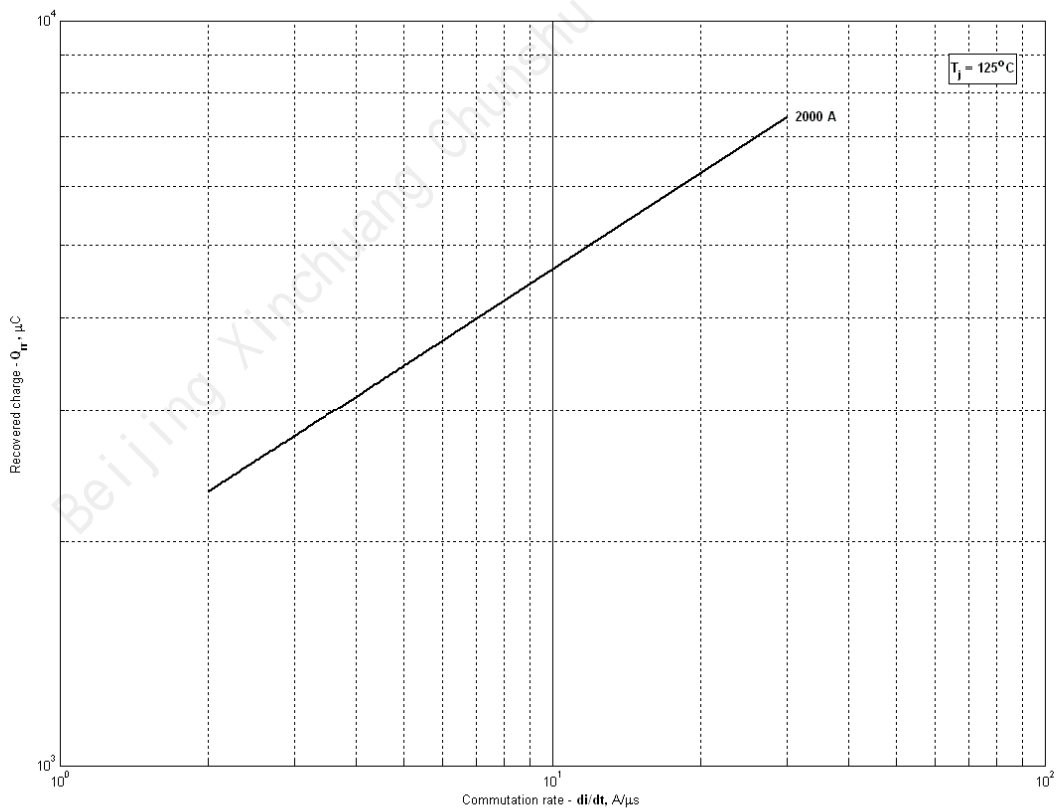


Fig 6 - Recovered charge, Q_{rr} (linear)

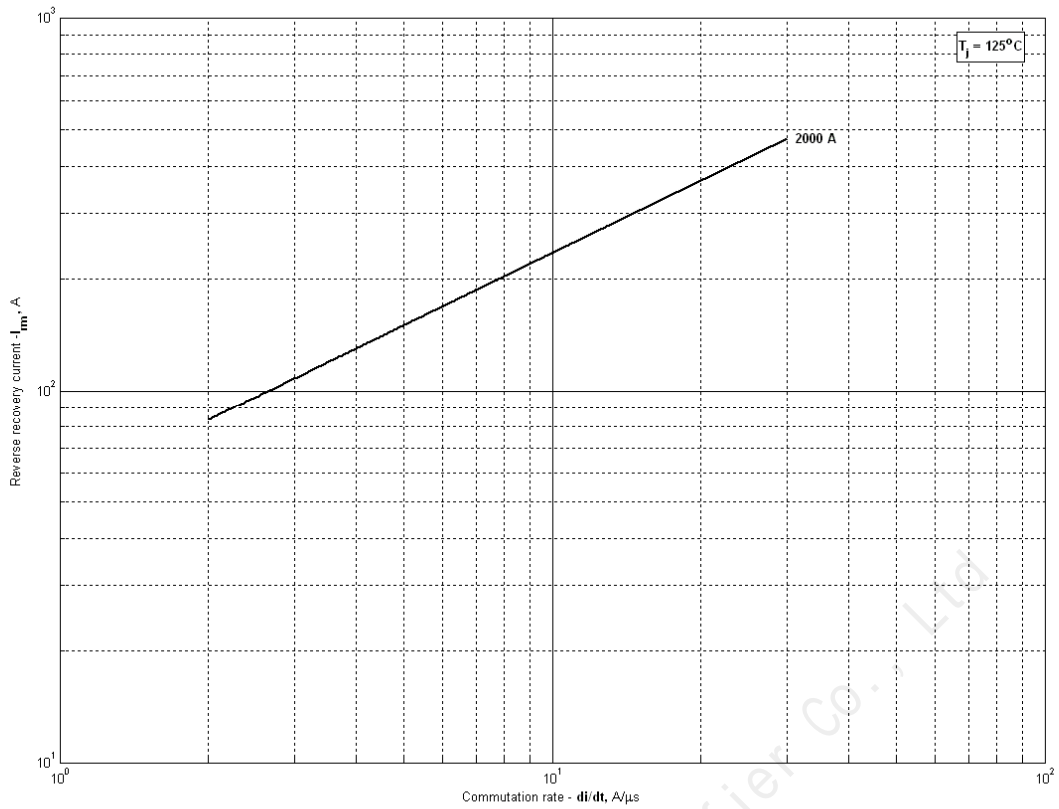


Fig 7 – Peak reverse recovery current, I_{rm}

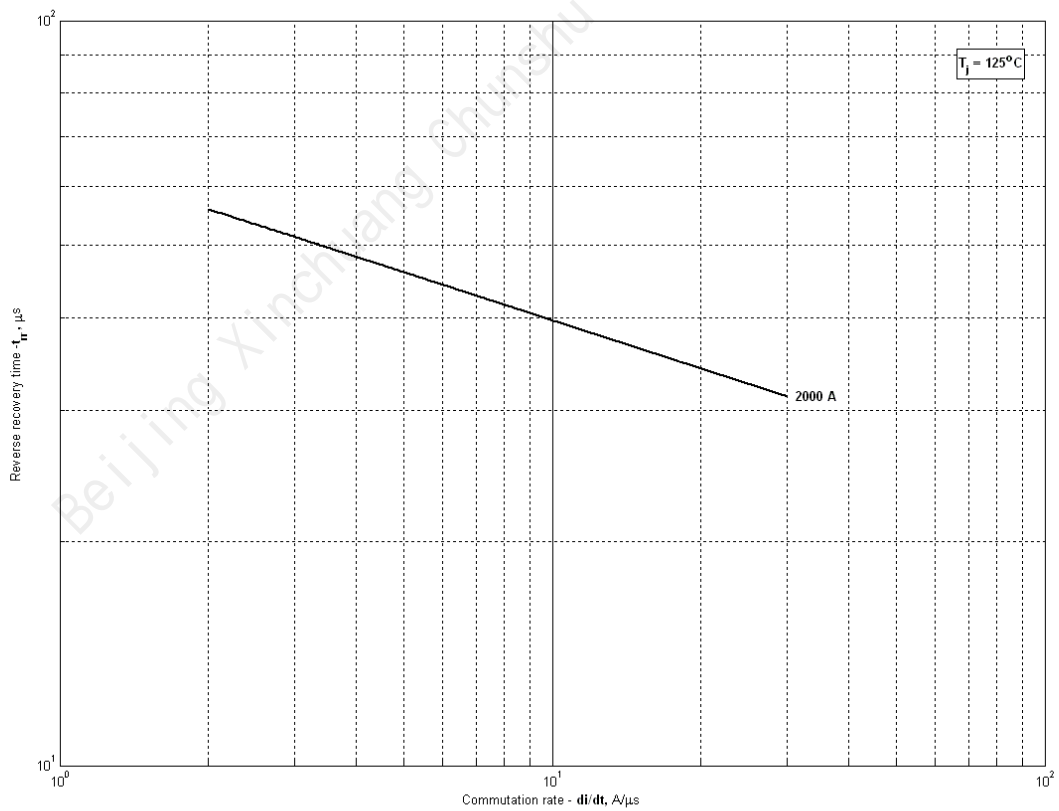


Fig 8 – Maximum recovery time, t_{rr} (linear)

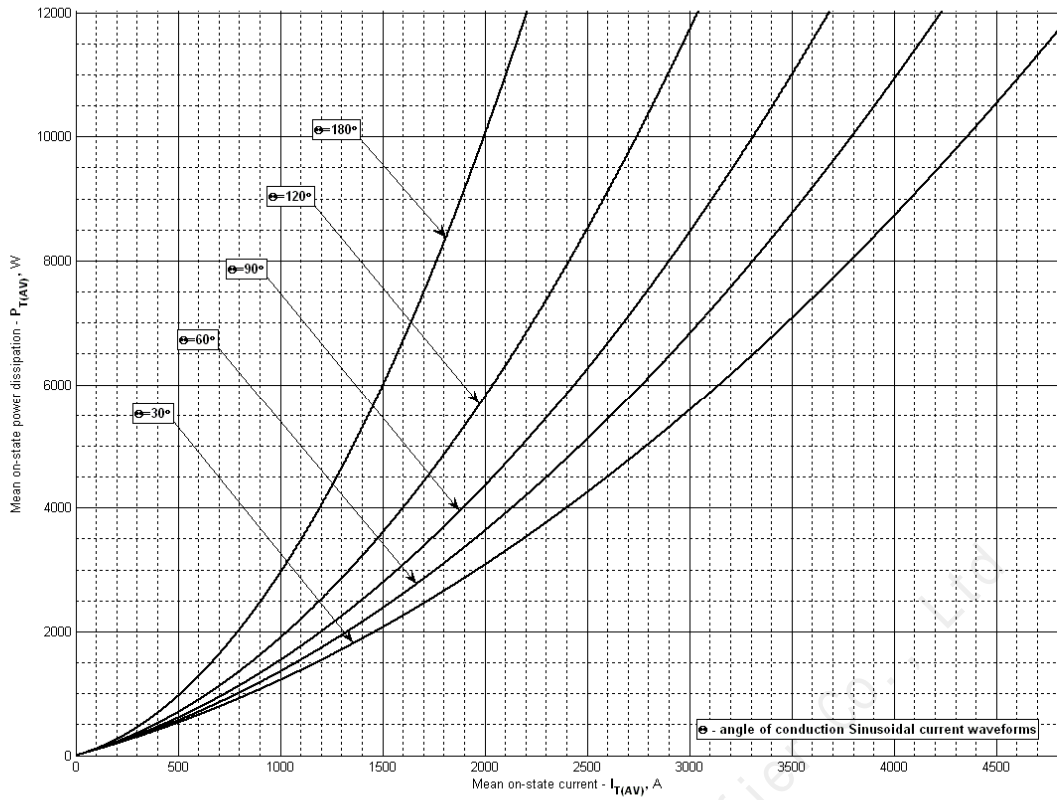


Fig 9 – On-state power loss (sinusoidal current waveforms)

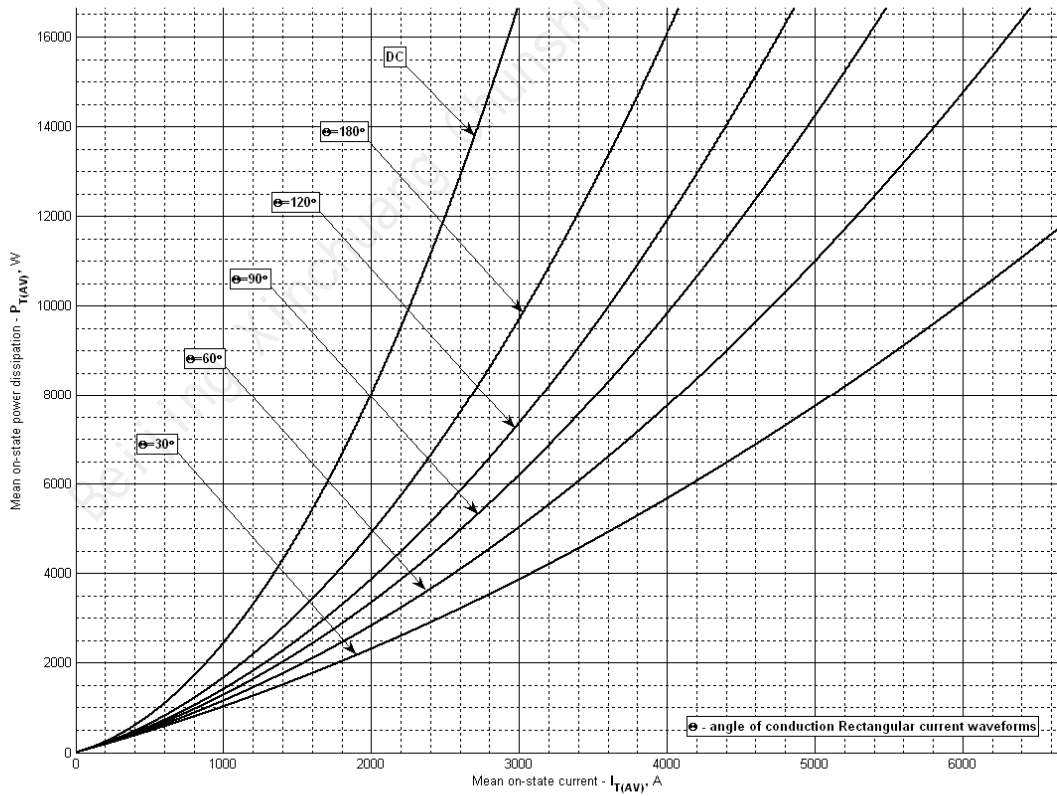


Fig 10 – On-state power loss (rectangular current waveforms)

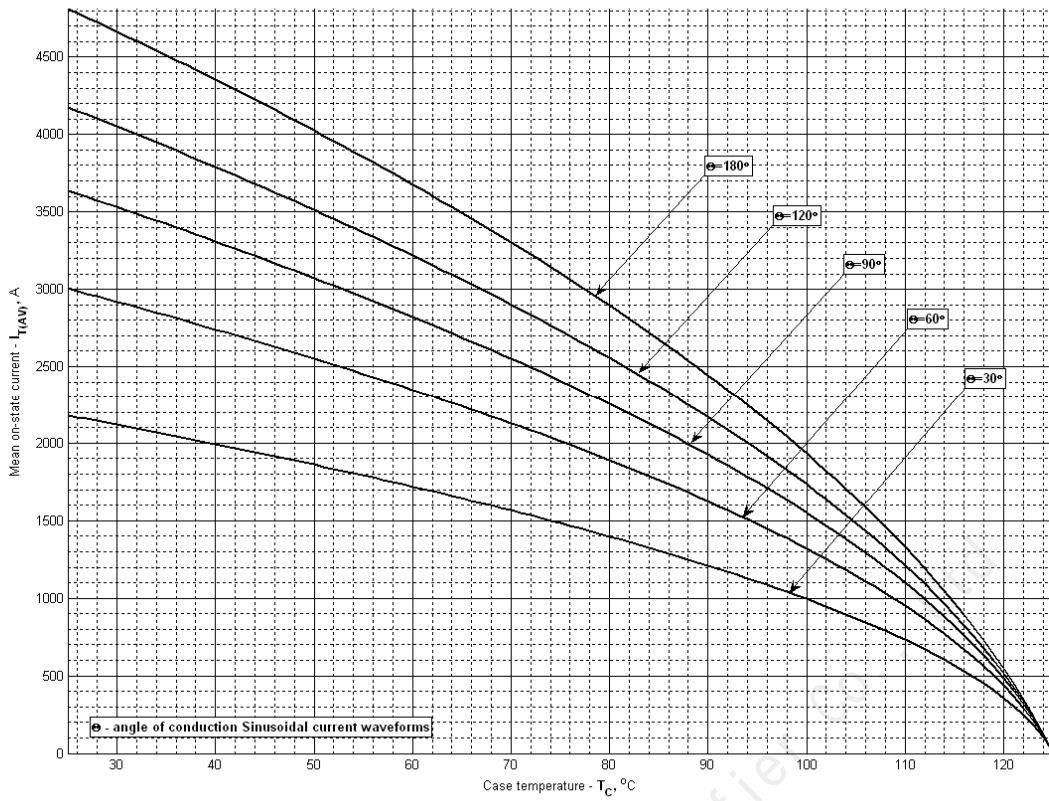


Fig 11 – Maximum case temperature DSC (sinusoidal current waveforms)

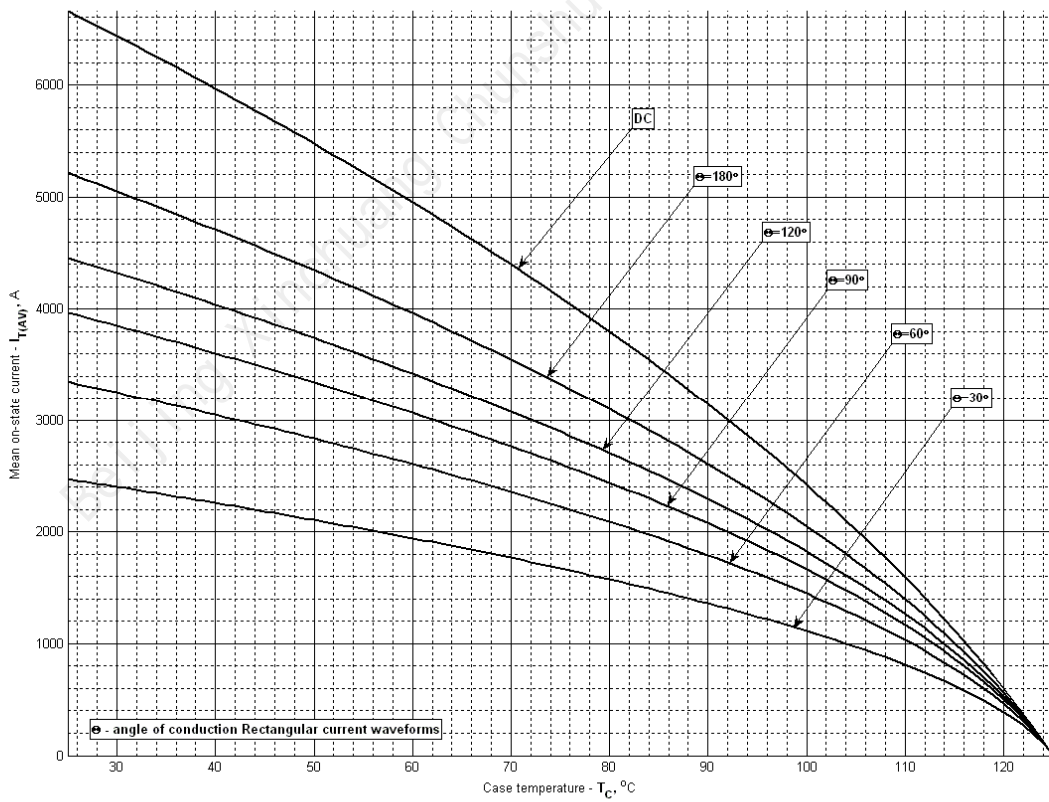


Fig 12 – Maximum case temperature DSC (rectangular current waveforms)

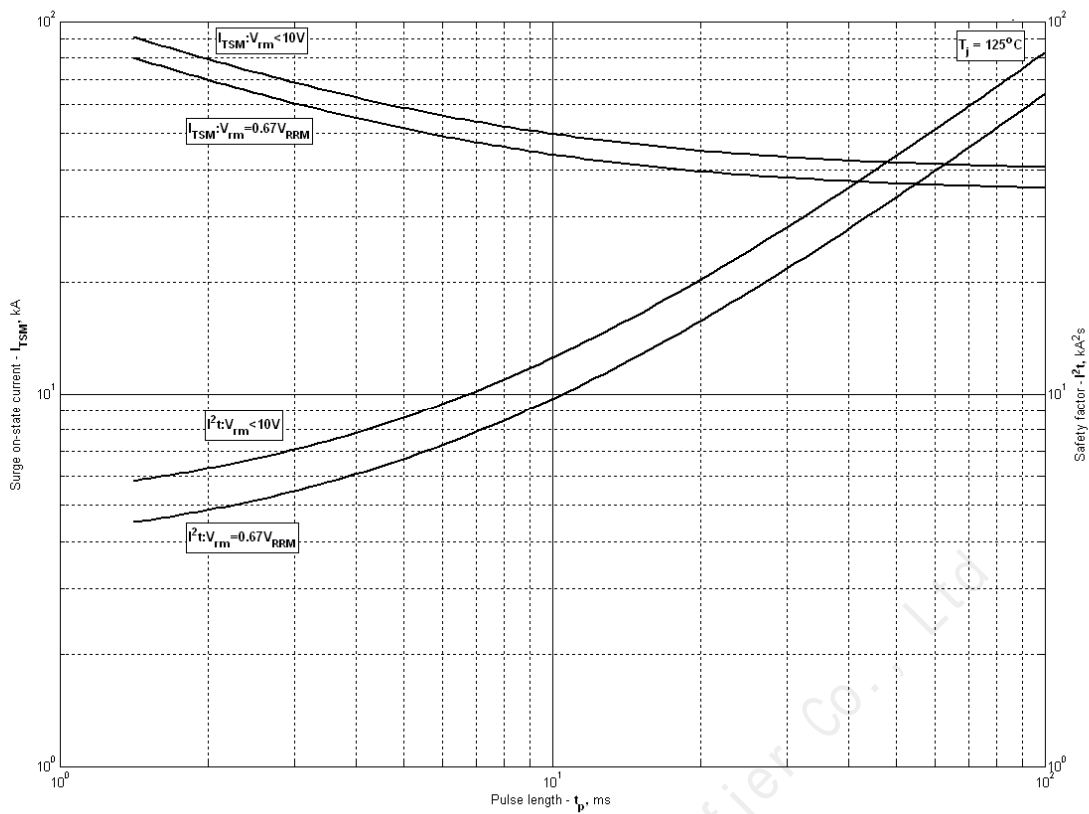


Fig 13 – Maximum surge and I^2t ratings

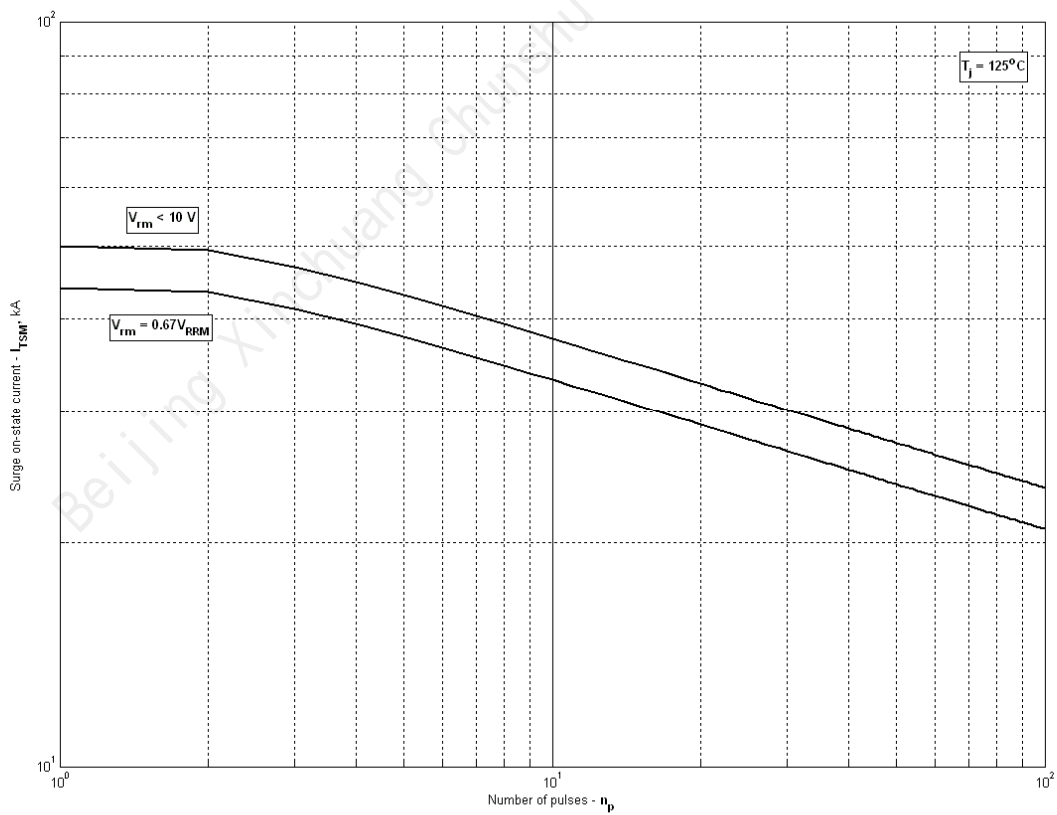


Fig 14 – Maximum surge ratings